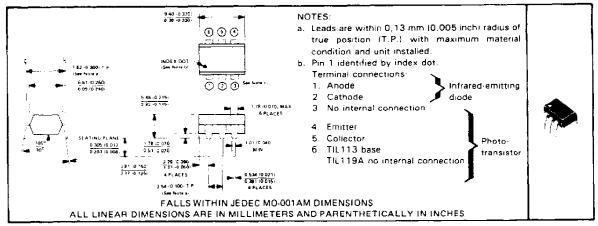
- Gallium Arsenide Diode Infrared Source Optically Coupled to a Silicon N-P-N Darlington-Connected Phototransistor
- High Direct-Current Transfer Ratio . . . 300% Minimum at 10 mA
- High-Voltage Electrical Isolation . . . 1500-Volt Rating
- Plastic Dual-In-Line Package
- Base Lead Provided on TIL113 for Conventional Transistor Biasing
- No Base Lead Connection on TIL119A for High-EMI Environments
- Typical Applications Include Remote Terminal Isolation, SCR and Triac Triggers, Mechanical Relays, and Pulse Transformers

mechanical data

The package consists of a gallium arsenide infrared-emitting diode and an n-p-n silicon darlington-connected phototransistor mounted on a 6-lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation and device performance characteristics remain stable when operated in high-humidity conditions. Unit weight is approximately 0.52 grams.



absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Input-to-Output Voltage
Collector-Base Voltage (TIL113)
Collector-Emitter Voltage (See Note 1)
Emitter-Collector Voltage
Emitter-Base Voltage (TIL113)
Input Diode Reverse Voltage
Input Diode Continuous Forward Current at (or below) 25°C Free-Air Temperature (See Note 2)
Continuous Power Dissipation at (or below) 25°C Free-Air Temperature:
Infrared-Emitting Diode (See Note 3)
Phototransistor (See Note 4)
Total (Infrared-Emitting Diode plus Phototransistor, See Note 5)
Storage Temperature Range
Lead Temperature 1,6 mm (1/16 Inch) from Case for 10 Seconds

1. This value applies when the base emitter diode is open circuited

- Derate linearly to 100°C free air temperature at the rate of 1.33 mA. C
- 3. Denote linearly to 100 C free air temperature at the rate of 2 mW/ $C_{\rm c}$
- Denste linearly to 100°C free air temperature at the rate of 2 mW/ C 5. Denate linearly to 100°C free-air temperature at the rate of 3.33 mW/ C

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing documents assessmenty include testing of all parameters.



TIL113, TIL119A OPTOCOUPLERS

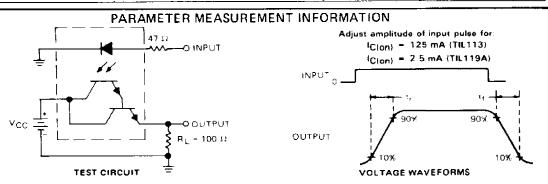
electrical characteristics at 25°C free-air temperature

PARAMETER				at .	TIL113		TIL119A			UNIT	
		1651	TEST CONDITIONS [†]			MIN TYP		MIN	TYP	MAX	UNTI
V(BR)CBO	Collector Base Breakdown Voltage	I _C = 10 μA,	ι _Ε - 0,	1 _F - 0	30						V
V(BR)CEO	Collector-Emitter Breakdown Voltage	I _C ÷ 1 mA.	+B = 0'	IF = 0	30			30			V
V(BR)EBO	Emitter-Base Breakdown Voltage	IE = 10 μA,	IC . 0'	1 _F - 0	7						V
V(BR)ECO	Emitter-Collector Breakdown Voltage	le = 10 μA.	lt = 0					7			٧
1	On State	VCE = 1 V.	ig 0,	1 _F = 10 mA	30	100					mA
¹ C(pn)	Collector Current	V _{CE} = 1 V.	I _F = 10 mA					30	160		
I _{C(off)}	Off-State Collector Current	V _{CE} = 10 V.	IB - 0,	1F - 0	i		100			100	пA
ηFE	Transistor Static Forward Current Transfer Ratio	V _{CE} - 1 V,	I _C - 10 mA.	le = 0		15,000					
v _F	Input Diode Static Forward Voltage	1p = 10 mA					1.5			1.5	V
	Collector-Emitter	Ic = 125 mA,	l _B = 0,	l _F = 50 mA	•		1.2				
VCE (sat)	Saturation Voltage	IC = 30 mA,	lp = 10 mA							1	
110	Input-to-Output Internal Resistance	V _{in-out} = +1.5 kV	, See Note 6		1011			1011			13
Cio	Input-to-Output Capacitance	V _{in out} 10,	f= 1 MHz.	See Note 6		1	13		1	1.3	pΕ

NOTE 6: These parameters are measured between both input-diode leads shorted together and all the phototransistor leads shorted together. *Reference to the base are not applicable to TiL119A.

switching characteristics at 25 C free-air temperature

	DADAMETED	DAMETED TEST CONDITIONS		TL113			TIL119A			UNIT
PARAMETER		15	TEST CONDITIONS			MAX	MIN	TYP	MAX	UNIT
ī,	Rise Time	V _{CC} - 15 V.	Iclon) = 125 mA,		300					
f	Fall Time	R _L = 100 Ω,	See Figure 1		300					μS
r	Rise Time	V _{CC} = 10 V.	I _{C(on)} = 2.5 mA,					300		
f	Fall Time		See Figure 1					300		448

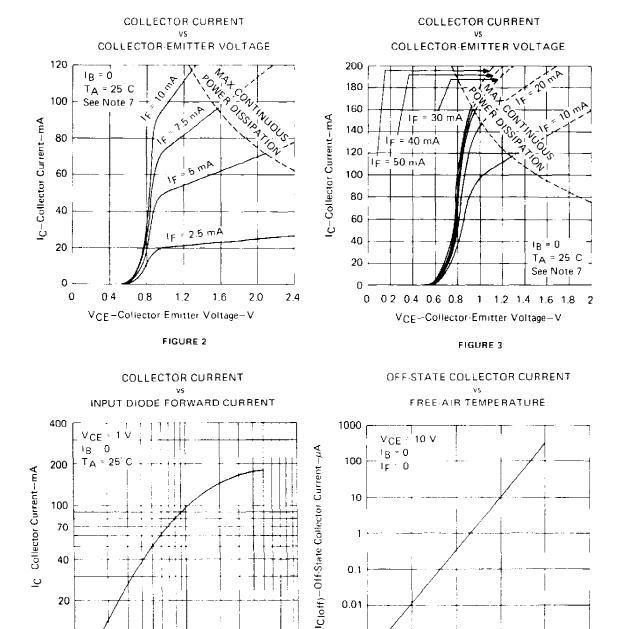


- NOTES: a The input waveform is supplied by a generator with the following characteristics: $Z_{out} = 50 \Omega_c t_f \approx 15 \text{ ns.}$ duty cycle $\approx 1\%$.
 - $t_W=500~\mu s$.

 b. The output waveform is monitored on an oscilloscope with the following characteristics: $t_r \lesssim 12~ns,~R_{in} \approx 1~M\Omega,~C_{in} \lesssim 20~pF$

FIGURE 1-SWITCHING TIMES

TYPICAL CHARACTERISTICS



NOTE 7. Pulse operation of input diode is required for operation beyond limits shown by dotted line.

20

10 Ip-Forward Current-mA

FIGURE 4

40

70 100

20

10

2



0.01

0.001

0

75

100

125

50

TA-Free-Air Temperature- C

FIGURE 5

0

-75 -50 -25

TYPICAL CHARACTERISTICS

TRANSISTOR STATIC FORWARD RELATIVE COLLECTOR-EMITTER SATURATION VOLTAGE **CURRENT TRANSFER RATIO** ٧S FREE AIR TEMPERATURE **COLLECTOR CURRENT** 1.6 25,000 VCE(sat)—Collector-Emitter Saturation Voltage IC = 125 mA VCE = 1 V hpe-Static Forward Current Transfer Ratio 1g = 0 |F = 0 1.4 IF = 50 mA $T_A = 25^{\circ}C$ Relative to Value at TA = 25°C 20,000 1.2 1.0 15,000 0.8 10,000 0.6 0.4 5,000 0.2

75 100 125

0

0.1

0.4

FIGURE 6

25 50

TA-Free-Air Temperature-°C

0

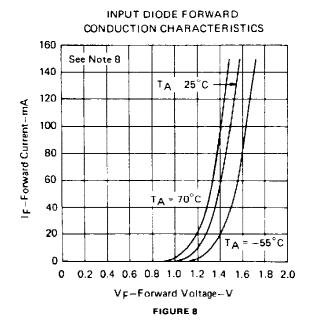
FIGURE 7

10

IC-Collector Current-mA

40 100

400 1000



NOTE 8: This parameter was massured using pulse techniques, t_w = 1 ms, duty cycle ≤ 2%.

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PACKAGE OPTION ADDENDUM

8-Apr-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TIL113	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI
TIL119	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI
TIL119A	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

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OBSOLETE: TI has discontinued the production of the device.

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TBD: The Pb-Free/Green conversion plan has not been defined.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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